



REV/ECN NO OR DESCRIPTION	REVISED	DATE
A PDR NO:1151223-3A	ROBIN	2016.08.10

- SPECIFICATIONS:
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC.
  - CONTACT RESISTANCE: 50mΩ MAX.
  - INSULATION VOLTAGE WITHSTAND:500V AC FOR ONE MINUTE.
  - UNLESS OTHERWISE SPECIFIED, TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT,IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
  - LIFE TEST: 5,000 CYCLES.
  - INSERTION FORCE: 0.3 - 3.0kg.
  - WITHDRAWAL FORCE: 0.3 - 3.0kg.
  - AFTER TEST CONTACT RESISTANCE: 120mΩ MAX.
  - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
  - MARKING: MARK "S" ON TOP OF CONNECTOR.
  - PACKING : TAPE & REEL.
  - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
  - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK: Ⓢ
  - HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING: Ⓢ

I	SHELL	1	COPPER ALLOY, 0.2t	Ni 60μ Min.
H	SEPARATOR	1	HIGH TEMP.THERMOPLASTIC	BLACK
G	MAKE TERMINAL	1	COPPER ALLOY, 0.2t	GOLD FLASH ON CONTACT AREA GOLD FLASH ON SOLDER AREA ALL OVER 50μ IN.
F	TRANSFER TERMINAL	1	COPPER ALLOY, 0.2t	
E	TIP SPRING	1	COPPER ALLOY, 0.2t	GOLD FLASH ON CONTACT AREA
D	RING A	1	COPPER ALLOY, 0.2t	MATE THE "B" ON SOLDER AREA
C	RING B	1	COPPER ALLOY, 0.2t	ALL OVER 50μ IN.
B	EARTH	1	COPPER ALLOY, 0.2t	
A	BODY	1	HIGH TEMP.THERMOPLASTIC	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: ANGLES:

X : ±0.5 X : ±2°

X.X : ±0.3 X.X : ±1°

XXX : ±0.2

Singatron Enterprise Co., Ltd.

信音企業股份有限公司

3.5Ø PHONE JACK

DWN ROBIN PART NO. 2S13095-10911F

CHKD BRUCE SCALE 4:1 UNIT: mm

APVD LUSSEN SIZE: A3 SHEET: 1 OF 1 REV: A

CUSTOMER COPY